



68K ColdFIRE[®]

M I C R O P R O C E S S O R S

Errata to **MCF5206e ColdFire Microprocessor** **User's Manual, rev. 3.0**

This errata describes corrections to the *MCF5206e User's Manual*. For convenience, the section number and page number of the errata item in the user's manual are provided.

To locate the latest updates for this document, refer to the world-wide web at <http://www.motorola.com/Coldfire>.

| | |
|--------------------|---|
| General | Every instance of “prescalar” should be changed to “prescaler.” |
| TOC, viii | Add an overbar to TS in paragraph number 2.5.5 listing Transfer Start (\overline{TS}) |
| TOC, xi | Add an overbar to TS in paragraph number 6.2.3 listing Transfer Start (\overline{TS}) |
| viii, TOC 2.10.1,2 | Change the designation of the two timer modules from Timer 1 and 2 to Timer 0 and 1. Change every instance of TIN[1] to TIN[0] and every instance of TIN[2] to TIN[1]. Similarly, change every instance of TOUT[1] to TOUT[0], and change TOUT[2] to TOUT[1]. |
| TOC, xiii | Change MARB to MPARK in section 8.4.1 Bus Master Arbitration Control. |

Freescale Semiconductor, Inc.

Changes

- 1.1, 1-1 Change the clock speed mentioned in the last sentence of the second paragraph from 45 MHz to 40 MHz.
- 1.2, 1-4 Change the clock speed mentioned in the third-to-last bullet item from 45 MHz to 40 MHz.
- 1.2.1.3, 1-10 Change the reference to Table 1-3 to Table 1-1 and change the designation of Table 1-2 to Table 1-1.
- 1.2.1.4, 1-10 Change the section designation from 1.2.1.4 to 1.3.1.4
- Add the following tables.

Table 1-2. ColdFire Effective Addressing Modes

| ADDRESSING MODES | SYNTAX |
|--|---|
| Register Direct Data Address | Dn An |
| Register Indirect Address Address with Postincrement Address with Predecrement Address with Displacement | (An) (An)+ -(An) (d ₁₆ ,An) |
| Address Register Indirect with Index 8-Bit Displacement | (d ₈ ,An,Xi) |
| Program Counter Indirect with Displacement | (d ₁₆ ,PC) |
| Program Counter Indirect with Index 8-Bit Displacement | (d ₈ ,PC,Xi) |
| Absolute Data Addressing Short Long | (xxx).W (xxx).L |
| Immediate | #<xxx> |

Freescale Semiconductor, Inc.

Changes

Table 1-3. MOVE Specific Effective Addressing Modes

| SOURCE <EA> | DESTINATION <EA> |
|--|-----------------------|
| Dn | All |
| An | All |
| (An) | All |
| (An)+ | All |
| -(An) | All |
| (d ₁₆ ,An) (d ₁₆ ,PC) | Dn |
| | An |
| | (An) |
| | (An)+ |
| | -(An) |
| (d ₈ ,An,Xi) (d ₈ ,PC,Xi) | (d ₁₆ ,An) |
| | Dn |
| | An |
| | (An) |
| | (An)+ |
| (xxx).W (xxx).L | -(An) |
| | Dn |
| | An |
| | (An) |
| | (An)+ |
| #<xxx> | -(An) |
| | Dn |
| | An |
| | (An) |
| | (An)+ |
| | -(An) |

1.2.1.5, 1-10

Change the section designation from 1.2.1.5 to 1.3.1.5.

1.3.17, 1-18

Change the clock speed mentioned in the first paragraph from 45 MHz to 40 MHz.

2.1, 2-1

Remove overbars from $\overline{PP[7:4]}$, $\overline{PST[3:0]}$, and the $\overline{4}$ over the arrow connecting $\overline{PP[7:4]}$ to the General Purpose I/O Port in Figure 2-1

Freescale Semiconductor, Inc.

Changes

2.1, 2-1

Change every instance of TOUT[1] to TOUT[0], and change TOUT[2] to TOUT[1]. In addition to the table of contents, such changes are required in the locations listed in the following table.

| Page | Section | Item |
|--------|-----------------|---------------------------|
| 2-1 | 2.1 | Figure 2-1 |
| 2-3 | 2.1 | Table 2-1 |
| 2-15 | 2.10 | first paragraph |
| | 2.10.1 | heading |
| | | first paragraph |
| | 2.10.2 | heading |
| | | first paragraph |
| 2.11.1 | first paragraph | |
| 2-21 | 2.17 | Table 2-12 |
| 14-3 | 14.4.1 | Table 14-1 |
| 14-6 | 14.4.1.5 | example code, Timer Init. |

2.1, 2-1

Insert the following text:

NOTE: The $\overline{\text{TRST}}$ signal does not work. All mention of this signal should be stricken from the book. To reset the JTAG TAP controller, TMS must be held high for 5 consecutive rising edges of TCK, as specified in IEEE 1149.1.

Strike out the signal name $\overline{\text{TRST}}$ as it appears in the following figures:

Figure 2-1 on page 2-1; Figure 16-1 on page 16-2; Figure 16-2 on page 16-7; Figure 16-3 on page 16-8; Figure 16-4 on page 16-9; Figure 17-16 on page 17-22, Figure 18-1 on page 18-2

Strike out the signal name $\overline{\text{TRST}}$ as it appears in the following tables:

Table of Contents, ix; Table 2-1, 2-3; Table 2-12, 2-21; strike both the name and signal description in Table 16-1, 16-3; Index, Index-7

2-3

Replace the following line in Table 2-1.

| | | | |
|---|---------------------------------|--|-----------|
| Test Reset/ Development Serial Clock | $\overline{\text{TRST}}$ /DSCLK | Asynchronous JTAG reset input/ Debug serial clock input | In/ In |
|---|---------------------------------|--|-----------|

with:

| | | | |
|--------------------------|-------|--------------------------|----|
| Development Serial Clock | DSCLK | Debug serial clock input | In |
|--------------------------|-------|--------------------------|----|

2.5.4, 2-9

Add an overbar to TS in Table 2-9 (ATM Encoding) column headings.

Freescale Semiconductor, Inc.

Changes

2.5.7, 2-11 The note at the top of the page should read as follows:

The internal synchronized version of \overline{ATA} is referred to as “internal asynchronous transfer acknowledge.” During a read cycle, data is latched on the rising edge of CLK when the internal asynchronous transfer acknowledge is asserted. Consequently, data must remain valid for at least one and a half CLK cycles after the assertion of \overline{ATA} . Similarly, during a write cycle, data is driven until the falling edge of CLK when the internal asynchronous transfer acknowledge is asserted.

2.14.3, 2-17 Replace section 2.14.3 with the following:

Development Serial Clock (DSCLK)

The DSCLK input signal is used as the development serial clock for the serial interface to the debug module, and is enabled when $MTMOD=1$. The maximum frequency for the DSCLK signal is 1/2 the CLK frequency. See **Section 15: Debug Support** section for additional information on this signal.

2.15.2, 2-18 Replace section 2.15.2 with the following note:

NOTE: The \overline{TRST} signal does not work. All discussion of this signal should be stricken from the book. To reset the JTAG TAP controller, TMS must be held high for 5 consecutive rising edges of TCK, as specified in IEEE 1149.1.

2.16.2, 2-20 Replace the last sentence in the first paragraph of section 2.16.2 with the following:

Note that \overline{HIZ} does not override JTAG operation.

2-21 Replace the following line in Table 2-12

| | | | | |
|-------------------------------------|------------------------------|-----------|-----------|---------|
| Test Reset/Development Serial Clock | \overline{TRST} / DSCLK | In/ In | Low/ - | -/ - |
|-------------------------------------|------------------------------|-----------|-----------|---------|

with

| | | | | |
|--------------------------|-------|----|---|----|
| Development Serial Clock | DSCLK | In | - | -- |
|--------------------------|-------|----|---|----|

3.2.2, 3-4 Add the following note.

NOTE:

Additional information about programming the 5206e integer MAC can be found in the Hardware Multiply/Accumulate section of the recently revised 5307 User’s Manual (rev. 2). While the 5206e MAC module is nearly identical to the 5307’s, the user is cautioned to be mindful of the differences – specifically the absence of fractional operand support on the 5206e.

Freescale Semiconductor, Inc.

Changes

3.4, 3-7 Change the label of bits 27 and 26 in Figure 3-5 from FS[3:0] to FS[3:2]

3.8, 3-15 The timing originally published in the 5206e manual for the multiply instructions were correct for the older 5206 which did not have a hardware multiplier-accumulator (MAC). Because the 5206e does have a MAC its multiply instructions execute substantially faster than was originally stated. Replace the following rows in Table 3-8:

| | | | | | | | | | |
|---------------------|---------|---------|---------|---------|---------|---------|---------|---------|--------|
| MULS.W | <ea>,Dx | 9(0/0) | 11(1/0) | 11(1/0) | 11(1/0) | 11(1/0) | 12(1/0) | 11(1/0) | 9(0/0) |
| MULU.W | <ea>,Dx | 9(0/0) | 11(1/0) | 11(1/0) | 11(1/0) | 11(1/0) | 12(1/0) | 11(1/0) | 9(0/0) |
| MULS.L ¹ | <ea>,Dx | 18(0/0) | 20(1/0) | 20(1/0) | 20(1/0) | 20(1/0) | — | — | — |
| MULU.L ¹ | <ea>,Dx | 18(0/0) | 20(1/0) | 20(1/0) | 20(1/0) | 20(1/0) | — | — | — |

with:

| | | | | | | | | | |
|--------|---------|--------|--------|--------|--------|--------|--------|--------|--------|
| MULS.W | <ea>,Dx | 4(0/0) | 6(1/0) | 6(1/0) | 6(1/0) | 6(1/0) | 7(1/0) | 6(1/0) | 4(0/0) |
| MULU.W | <ea>,Dx | 4(0/0) | 6(1/0) | 6(1/0) | 6(1/0) | 6(1/0) | 8(1/0) | 6(1/0) | 4(0/0) |
| MULS.L | <ea>,Dx | 6(0/0) | 8(1/0) | 8(1/0) | 8(1/0) | 8(1/0) | - | - | |
| MULU.L | <ea>,Dx | 6(0/0) | 8(1/0) | 8(1/0) | 8(1/0) | 8(1/0) | - | - | |

3.8, 3-15 Replace the timing information for the DIVS.L and DIVU.L instructions with the following:

| | | | | | | | | | |
|--------|---------|---------|---------|---------|---------|---------|--|--|--|
| DIVS.L | <ea>,Dx | 35(0/0) | 37(1/0) | 37(1/0) | 37(1/0) | 37(1/0) | | | |
| DIVU.L | <ea>,Dx | 35(0/0) | 37(1/0) | 37(1/0) | 37(1/0) | 37(1/0) | | | |

3.8, 3-16 Add the following rows containing the remainder instruction (REMU and REMS) timing to Table 3-8:

| | | | | | | | | | |
|--------|---------|---------|---------|---------|---------|---------|--|--|--|
| REMS.L | <ea>,Dx | 35(0/0) | 37(1/0) | 37(1/0) | 37(1/0) | 37(1/0) | | | |
| REMU.L | <ea>,Dx | 35(0/0) | 37(1/0) | 37(1/0) | 37(1/0) | 37(1/0) | | | |

3.9, 3-17 Add the following line to Table 3-9 (Miscellaneous Instruction Execution Times) describing the timing of the “Push and Invalidate Cache Line” instruction.

| | | | | | | | | | |
|--------|-----------|---|---------|---|---|---|---|---|---|
| CPUSHL | (bc),(Ax) | — | 11(0/1) | — | — | — | — | — | — |
|--------|-----------|---|---------|---|---|---|---|---|---|

3.9, 3-17 In Table 3-9, strike out the timing information for the WDDATA #xxx instruction. In 52xx devices the WDDATA instruction only supports memory operands.

4.2, 4-2 Annotate Figure 4-1 to correct the following errors.

The tag array should compare bits 31-12, not bits 31-9.

The tag array elements should be numbered from 0-255, not 0-31.

The data array elements should be numbered 0-1023, not 0-127.

Freescale Semiconductor, Inc.

Changes

- 6.2.7, 6-3 Add an overbar to TS in Table 6-3 (ATM Encoding) column headings.
- 6.7, 6-49 Delete the following sentence from paragraph three as shown:
~~An interrupt must be held valid for at least two consecutive CLK periods to be considered a valid input.~~
- 6.7, 6-49 Change the note on page 6-49 to read as follows:

NOTE:

All interrupts are level sensitive and must remain stable and valid until the interrupt is acknowledged for the interrupt to be reliably detected. Interrupt 7 is both level sensitive and edge sensitive.

- 6.7.1, 6-52 Add the following paragraph before the note.
- A chip select can be programmed to assert during the interrupt acknowledge cycle by mapping the chip select address to the \$7FFFFFFF appearing on A[27:5]. For example, setting CSAR1= \$07FF causes $\overline{CS1}$ to assert during the interrupt acknowledge cycle.
- 6.11.1, 6-82 Correct the \overline{RSTO} , \overline{BD} , and \overline{BR} signals in Figure 6-49 to show them remaining in a high impedance state until \overline{RSTI} and \overline{HIZ} are negated.
- Add an inversion bar above “HIZ” in Figure 6-49.

Correct the second paragraph to read as follows:

\overline{TS} must be pulled up or negated during master reset. ~~When the assertion of \overline{RSTI} is recognized internally, the MCF5206e asserts the reset out pin (\overline{RSTO}). \overline{RSTO} is asserted as long as \overline{RSTI} is asserted when \overline{RSTI} is negated, and remains asserted for 32 CLK cycles after \overline{RSTI} is negated. For proper master reset operation, \overline{RSTI} and \overline{HIZ} must be asserted and negated simultaneously.~~

Add the following sentence to the last paragraph.

With the assertion of \overline{TS} , reset exception processing starts 54 clock cycles after \overline{RSTI} is negated.

- 6.11.2, 6-83 Add an inversion bar above “HIZ” in Figure 6-50.
- Correct the second paragraph to read as follows:

\overline{TS} must be pulled up or negated during normal reset. ~~When the assertion of \overline{RSTI} is recognized internally, the MCF5206e asserts the reset out pin (\overline{RSTO}). \overline{RSTO} is asserted as long as \overline{RSTI} is asserted when \overline{RSTI} is negated, and remains asserted for 32 CLK cycles after \overline{RSTI} is negated. For proper normal reset operation, \overline{HIZ} must be negated as long as \overline{RSTI} is asserted.~~



Freescale Semiconductor, Inc.

Changes

6.11.2, 6-84 Change the last sentence to read:
The $\overline{\text{IPL}}[2:0]$ signals are internally synchronized on consecutive falling and rising clocks in a manner identical to $\overline{\text{RSTI}}$ and $\overline{\text{HIZ}}$.

7.3, 7-3 Add the following text:
NOTE: When reading the four DMA source and destination registers (DMA0SAR, DMA1SAR, DMA0DAR, DMA1DAR), the data for bits [7:0] will echo the data on bits [15:8]. Writes to these registers function normally. If the source increment (SINC) or destination increment (DINC) bit of the DMA control register is set, the SAR and DAR registers will increment, respectively, with each transfer.

This behavior complicates observation of DMA transfers since the user generally cannot read a correct value from SAR or DAR. The progress of DMA transfers can be monitored by reading the DMA byte count register.

7.3, 7-3 Replace the first note with the following:

NOTE: The DMA cannot access the SRAM that is resident on-chip. Nor can it perform transfers in or out of the on-chip peripherals. Use the core CPU to access on-chip peripherals.

7.4.4, 7-8 In the discussion of the auto-align field, change the reference to the auto alignment section from 7.10.2.2 to 7.7.2.2.

7.4.5, 7-11 Add the following note describing the action of the DONE bit.

NOTE:

Setting the DONE bit does not change any other DMA programming nor disable the channel. An aborted transfer is restarted if another DMA request is received (for example, from an external asynchronous source) before the DMA channel has been reprogrammed but after the DONE bit is set.

7.4.6, 7-12 The last sentence mentioning $\overline{\text{SMEN}}$ and $\overline{\text{SIVOE}}$ actually refers to internal signals that the user should not be concerned with. Strike it out.

~~The register is selected when both the $\overline{\text{SMEN}}$ and $\overline{\text{SIVOE}}$ signals are asserted.~~

7.5.1, 7-12 Add the following paragraphs.

7.5.1.1 Exceptions to Normal Cycle Steal Operation

When the cycle steal (CS) mode is set in DCR, the DMA controller module does not perform a single read/write transfer if multiple channels are active. For example:

- if DMA channel 1 is set to cycle steal mode,
- and the first request for DMA channel 1 has already occurred,
- and then a second DMA channel is started,

then, instead of a single transfer, DMA channel 1 will completely transfer the number of bytes programmed in the BCR, thus ignoring the setting of the cycle steal mode bit. Using only the lowest priority channel in cycle steal mode avoids this behavior.

7.6.1, 7-13 Add the following paragraph.

7.6.1.1 DMA to External DRAM

When accessing external DRAM with a DMA channel in single address mode DCR[S_RW] controls the DRAMW pin as well as R/W, and the DRAM controller still initiates a TA signal internally. The size pins, SIZ[1:0], are driven by the processor when it has control of the bus and can be decoded along with other signals to create a DMA acknowledge.

7.7.1.1, 7-14 Add the following paragraphs.

7.7.1.1.1 Some Considerations Regarding Internal Bus Arbitration and DMA Writes

To ensure all DMA write requests are serviced, even under unusual circumstances, do one or both of the following.

- Use processor writes to set the DMA start bits. That is, do not set the external DMA request bit DCR[EEXT].
- If multiple DMA channels are used concurrently, then have only a single channel running instantaneously by using the external DMA request.

7.7.1.2, 7-15 Add the following paragraphs.

7.7.1.2.1 Some Considerations When Using Multiple Channels

When multiple internal DMA channels are used, the previously active channel's DCR[SINC] value is used for the first DMA transfer on the newly active channel. This effect is only observable when the active channel is interrupted during a transfer by a DMA request from another channel, and one channel is programmed to increment its source address register (SAR) while the other is not.

For example, when channel 2 gets the bus, it's SAR will increment after the first transfer if the following two conditions are met.

- DMA channel 1 is programmed to increment source addresses and channel 2 is not
- channel 2 initiates a DMA request while channel 1 is doing a transfer

This could cause complications if channel 2 was being used as a FIFO.

Furthermore, if:

- channel 1 is programmed not to increment its SAR but channel 2 is set to increment,
- and channel 2 initiates a DMA request while channel 1 is doing a transfer,

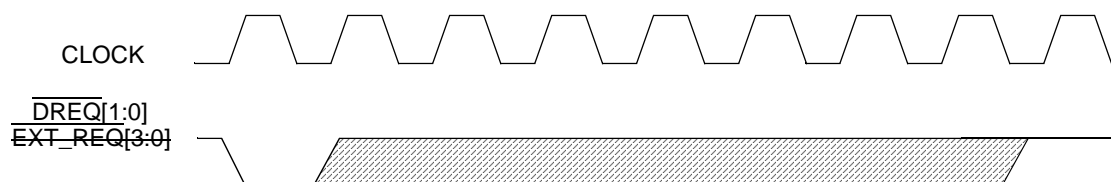
then when channel 2 gets the bus, it's SAR is controlled by the previously active channel setting and does not increment after the first transfer. While channel 2's SAR does increment after all subsequent transfers, two writes in the same address occur.

This behavior can be avoided by one or both of the following strategies:

- ensure no multiple concurrent internal DMA requests
- ensure all DMA channels have identical incrementing schemes (that is, DCR[SINC] is programmed the same for all channels).

7.7.2.1, 7-15 Change the reference to Figure 7-7 to read Figure 7-6.

7.7.2.1, 7-16 Change the $\overline{\text{EXT_REQ}}[3:0]$ signal name in Figure 7-6 to $\overline{\text{DREQ}}[1:0]$ as follows:



7.7.2.1, 7-16 Add the following paragraphs.

7.7.2.1.1 $\overline{\text{DREQ}}$ Timing In Cycle Steal Mode

In cycle-steal mode ($\text{DCR}[\text{CS}] = 1$), the read/write transaction is limited to a single transfer. $\overline{\text{DREQ}}$ must be negated appropriately to avoid generating another request. For dual-address transfers, $\overline{\text{DREQ}}$ must be negated before $\overline{\text{TS}}$ is asserted for the write portion. For single-address transfers, $\overline{\text{DREQ}}$ must be negated before $\overline{\text{TS}}$ is asserted for the transfer.

NOTE:

Additional timing diagrams depicting $\overline{\text{DREQ}}$ and other DMA transaction signals can be found in the DMA section of the recently revised MC5307 User's Manual. Although the 5307 and 5206e share the same DMA module, the user is cautioned to be mindful of their differences when applying 5307 data to 5206e designs.

8.2.5, 8-6 Add the following paragraphs:

8.2.5.1 Special Conditions Involving Level 7 Interrupt

Under certain conditions the execution of a MOVE to SR or RTE instruction which may cause a level 7 interrupt request to go undetected by the processor (that is, the core never responds with a level 7 interrupt exception).

Level 7 interrupts are treated differently than all other interrupts since they are edge-sensitive (versus level-sensitive). The processor has special logic to recognize the high-to-low assertion edge of the active-low interrupt 7 request. During a very small window of time when a level 7 interrupt request is asserted while the processor is executing certain variations of the MOVE to SR or RTE instructions, the processor will ignore the interrupt request. This ignorance only occurs when the execution of the MOVE to SR or RTE instruction loads a value of "7" into the 3-bit interrupt mask level of the status register.

NOTE:

The typical level 7 interrupt service routine, where the interrupt request is negated before the RTE is executed, does not cause a level 7 interrupt to go undetected.

To ensure all the level 7 interrupts are detected, load an operand of "6" into the 3-bit interrupt mask of the status register to mask interrupt levels 1-6 for the MOVE to SR or RTE instructions. The use of this new interrupt mask level does not effect the ability to inhibit interrupts, since values of 6 or 7 both mask levels 1-6. A level 7 interrupt service routine would need to load an operand of "7" into the interrupt mask until the level 7 interrupt source is negated, otherwise another level 7 interrupt would be generated if the interrupt mask is lowered and the level 7 request is still present.

8.2.5, 8-4 Delete the following sentence from paragraph one as shown:

~~An interrupt must be held valid for at least two consecutive CLK periods to be considered a valid input.~~

Freescale Semiconductor, Inc.

Changes

- 8.3.2.1, 8-8 Change the heading of the first paragraph following the MBAR register figure to read, “BA[31:14] – Base Address”, to show that only bits 31 through 14 are valid address bits.
- Modify the register diagram to show only bits 31 through 14 are valid. Bits 13, 11, 12 and 13 are reserved.
- 8.3.2.4, 8-12 Replace the last paragraph of this section with the following:
- At system reset, all unreserved bits are set. The IMR is a 16-bit read/write register except for bits [15:14]. These bits always read as 0. Writes to IMR[15:14] function normally. If reads of IMR[15:14] are required, store the written value in a separate memory location whenever IMR is updated.
- 8.3.2.4, 8-12 Modify the Interrupt Mask Register diagram to show 1 as the reset state for DMA0 and DMA1.
- 8.3.2.10, 8-16 Change the second paragraph to read as follows:
- The PAR is an 8- 16-bit read-write register. At system reset, all bits are cleared.
- Add the following paragraph.
- “PAR15 – PAR10 Pin Assignment Bits 15 -10 Unused.”
- The heading for the PAR9 bit discussion should follow the register figure, rather than precede it. Annotate accordingly.
- 8.3.2.10, 8-17 In discussion of PAR bit 4, change the words “Parallel Port” to “general purpose I/O” as shown below.
- 0 = Output ~~Parallel Port~~ general purpose I/O signals PP3 - PP0 on PP[3:0]/DDATA[3:0] pins
- 8,9.1, 8-18 Change MARB to MPARK in the section title and the first paragraph.
- Change the register figure annotation as follows:
“Bus Master Arbitration Control (~~MARB~~) (MPARK)”
- 9.3.3.1, 9-9 Add the following paragraph.
- Figure 9-2 also applies to auto-acknowledge mode with zero wait states. For nonzero wait states, the same timing diagram applies with the specified number of wait states inserted between C1 and C2. When running back-to-back asynchronous transfers to the same peripheral, the minimum time between deasserting CS and then reasserting it is one clock cycle.

9.3.3.1, 9-9 Add the following paragraphs.

9.3.3.1a Nonburst Transfer with Address Setup, No Address Hold, No Wait State.

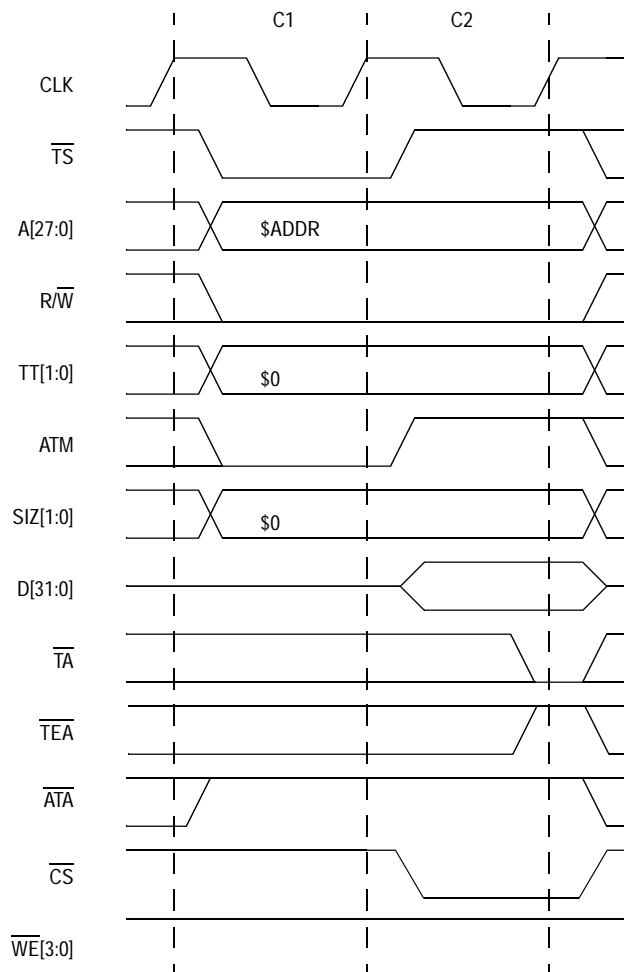


Figure 1. Longword Write Transfer from a 32-Bit Port (Address Setup, No Wait State, No Address Hold)

Clock 1 (C1)

The write cycle starts in C1. During C1, the MCF5206e places valid values on the address bus (A[27:0]) and transfer control signals. The transfer type (TT[1:0]) signals identify the specific access type and access type and mode (ATM) is driven low to identify the transfer as data. The read/write (R/W) signal is driven low for a write cycle, and the size signals (SIZ[1:0]) are driven low to indicate a longword transfer. The MCF5206e asserts transfer start (TS) to indicate the beginning of a bus cycle. Note $\overline{\text{WE}}[3:0]$ are never asserted.

Clock 2 (C2)

During C2, the MCF5206e asserts the appropriate chip select ($\overline{\text{CS}}$) for the address being accessed, negates transfer start ($\overline{\text{TS}}$), drives access type and mode (ATM) high to identify the transfer as supervisor, and drives data onto D[31:0]. If the selected device(s) is ready to latch the data, it latches D[31:0] and asserts the transfer acknowledge ($\overline{\text{TA}}$). At the end of C2, the MCF5206e samples the level of $\overline{\text{TA}}$. If $\overline{\text{TA}}$ is asserted, the transfer of the longword is complete, and the MCF5206e negates $\overline{\text{CS}}$ after the next rising edge of CLK. If $\overline{\text{TA}}$ is negated, the MCF5206e continues to sample $\overline{\text{TA}}$ and inserts wait states instead of terminating the transfer. The MCF5206e continues to sample $\overline{\text{TA}}$ on successive rising edge of CLK until it is asserted. If the bus monitor timer is enabled and $\overline{\text{TA}}$ is not asserted before the programmed bus monitor time is reached, the cycle is terminated with an internal bus error.

- 9.3.3.6, 9-18 Add an overbar to TS in Figure 9-7, signal label. Also, in that same figure, add overbars to the following signal names as shown: R/W, $\overline{\text{TA}}$, $\overline{\text{TEA}}$, $\overline{\text{ATA}}$, $\overline{\text{CS}}$, $\overline{\text{WE}}[3:0]$
- 9.4.2.3, 9-34 Add the following sentence to the first paragraph.
Setting ASET delays the assertion of $\overline{\text{CS}}$ for both reads and writes.
- 10.2, 10-1 Change the reference in the last sentence to the SIM subsection from 6.3.2.10 to 8.3.2.10.
- 10.3.1, 10-1 Change every reference to port A data direction register from PPDDR to PADDR. For example, Table 10-1, first row.
Change every reference to port A data register from PPDAT to PADAT. For example, Table 10-1, second row.
- 10.3.1, 10-2 Change port A data register diagram label from PPDAT to PADAT.

Freescale Semiconductor, Inc.

Changes

10.3.2.1, 10-2 Correct the output pin column of Table 10-2 to read as follows:

Table 10-2. Data Direction Register Bit Assignments

| Data Direction Register Bit | OUTPUT PIN |
|-----------------------------|----------------|
| DDR7 | PP[7]/PST[3] |
| DDR6 | PP[6]/PST[2] |
| DDR5 | PP[5]/PST[1] |
| DDR4 | PP[4]/PST[0] |
| DDR3 | PP[3]/DDATA[3] |
| DDR2 | PP[2]/DDATA[2] |
| DDR1 | PP[1]/DDATA[1] |
| DDR0 | PP[0]/DDATA[0] |

10.3.2.2, 10-3 Correct the designation of Table 10-4 to read Table 10-3.

11.3.2.6, 11-13 Table 11-8, change the column heading from CAS to “Column Address.”

Add the following paragraphs.

Tables 11-6, 11-7, and 11-8 and the associated text describe connections for symmetrical DRAM. If your DRAM is asymmetrical (different number of column and row addresses) then the instructions accompanying Tables 11-6, 7, and 8 are not sufficient. The following procedure allows correct design of asymmetrical DRAM connections using Tables 11-6, 7, and 8.

1. Find the table corresponding to your DRAM port and page size.
2. Starting from the bottom of the table, assign DRAM address pins using only the shaded connections until you run out of column addresses.
3. Continue following the table to make the remaining connections, but now use every address line (not just the shaded lines) until you have connected all of the address pins on your DRAM.

Freescale Semiconductor, Inc.

Changes

Here is an example:

If you wanted to connect a 32-bit, 1Kbyte page size with 8 column address lines and 11 row address lines then you would use the connections shown in the table below.

Table 2-3. 32-bit Port Size, 1 KB Page Size Asymmetrical DRAM Connections

| 5206e Address Pin | DRAM Address Pin | Column Address Line | Row Address Line |
|-------------------|------------------|---------------------|------------------|
| A10 | 0 | Y | Y |
| A11 | 1 | Y | Y |
| A12 | 2 | Y | Y |
| A13 | 3 | Y | Y |
| A14 | 4 | Y | Y |
| A15 | 5 | Y | Y |
| A16 | 6 | Y | Y |
| A17 | 7 | Y | Y |
| A18 | 8 | | Y |
| A19 | 9 | | Y |
| A20 | 10 | | Y |

11.3.2, 11-15

In the third line change DCMR: \$001E0000 to \$003E0000.

11.5, 11-61

Change the second sentence in the first paragraph to read 1 MByte instead of 4 MByte.

Change the last sentence in the first paragraph from (1 MByte x 32) to (256 KByte x 32).

Change the transfer address mask bit range for the DCMR0 in the second paragraph from 18 - 16 to 19 - 17. (This appears on the second to last line on the page.)

11.5, 11-62

Change the address range upper bound for the DRAM initialization example from \$001EFFF to \$001FFFFFF.

Change the commentary in the code example from - 0x001effff to - 0x001ffff

12, 12-1

Add the following paragraphs:

NOTE:

Throughout the document, “system clock” refers to the main processor clock.

To select internal clock for both transmit and receive, load UCSR with 0xDD.

12.3.1, 12-5 Add the following paragraphs.

12.3.1.1 Calculating Baud Rates

The desired baud rate is specified by the following formula:

$$\text{UBG1 and UBG2} = (\text{system clock}/(\text{baudrate} * 32))$$

For example, to select 19200 baud, write 0x0 to UBG1 and 0x57 to UBG2. See the UART section of the 5307 User's Manual (Rev. 2.0) for more information.

12.3.1, 12-5 Add the following paragraphs.

For example, the maximum UART baud rate using an external clock, TIN, is computed as follows.

Note that the maximum TIN frequency corresponds to the minimum period. From Table 17-10, the minimum TIN cycle time (T1) is specified as 3 clocks, indicating a maximum operating frequency of one-third the system clock. The maximum processor clock rate is 54 MHz, giving a maximum baud of $54 \div 3$, or 18 MHz.

12.4.1.12, 12-5 Add the following note.

NOTE:

See the UART section of the recently revised MCF5307 User's Manual (rev 2.) for additional information. Although the 5307 and 5206e share the same UART module, the user is cautioned to be mindful of their differences when applying 5307 data to 5206e designs.

12.5, 12-34 Strike out the second sentence beginning on the fifth line with, "However, if the UART Interrupt Control Register. . ."

12.5, 12-35-39 Change the figure numbers on the UART Software Flowchart from "11-" to "12-".

13.5.2, 13-7 Annotate the next to last sentence to read as follows:

The serial bit clock frequency is equal to the CPU clock divided by the divider shown in Table 13-2. ~~which also shows the serial bit clock frequency for a 33MHz internal operating frequency~~

Add the following paragraphs:

The M-Bus frequency depends on the CPU frequency and is calculated according to the following formula:

$$\text{M-Bus frequency} = \text{CPU frequency}/(\text{selected divider})$$

The user specifies a divider by writing its MBC5-0 value (shown in Table 13-2) into MFDR. For example, writing 0x07 into MFDR specifies a divider of 68. A divider value must be chosen large enough to ensure the resulting M-Bus frequency is always less than 100 KHz.

13.6.6, 13-14 Add the following paragraph:

In slave mode, the module will only respond to its address and will not recognize I²C 'general call' (address 0) messages. Also in slave mode, there is no interrupt for the stop condition so users must detect the end of a transmission either by counting bytes or by polling for the stop condition.

14.5, 14-9 Add the following paragraphs.

14.5 Programming Example

Given a system clock of 40.550400 MHz, program a timer to generate one pulse every millisecond. The formula to calculate the timeout period for the timer is shown below.

Timeout = (1/clock) × (1 or 16) × (TMR prescale value + 1) × [timer reference register]

We get the desired result by setting the TMR prescale value, TMR[PS7-PS0], to zero (yielding a divisor of 1), and loading the timer reference register, TRR[15:0], with 0x9E66.

Timeout = (1/40,550,500) × (1) × (1) × (0x9E66) seconds

Timeout = (2.466e-8) × (40550) seconds

Timeout = 0.001 seconds

15.2.2, 15-6 Add the following paragraphs:

15.2.2.1 Debug Captured Write after Exception may cause an Extraneous PST = 0x1

There is a complex sequence of events that may cause the Version 2 debug module to output an extraneous PST=1 value when capturing and displaying operand write data. The specific sequence is:

4. The processor takes any type of exception.
5. Once the exception handler is entered, the very first operand to be captured and displayed by the PST/DDATA logic is an operand write.
6. If the next instruction after the operand write is a non-memory-referencing opcode (e.g., a register-to-register or immediate-to-register instruction), then the debug module may incorrectly output an extraneous PST = 0x1 value before the write operand is captured and displayed.

The resulting stream of PST values is as follows:

Table 15-1.5. PST Values

| PST | PST[3:0] Stream (HEX) | | | | | | | | | | | | | | | |
|------------------|-----------------------|---|-----|---|---|-----|----------|---|-----|----------------|---|-----|------------|---|---|----|
| Current | C | C | ... | 5 | 0 | ... | 1 | 0 | ... | 1 | 0 | ... | [89B] | 1 | 0 | .. |
| Correct | C | C | ... | 5 | 0 | ... | 1 | 0 | ... | 0 | 0 | | [89B] | 1 | 0 | .. |
| Position Comment | exception | | | | | | wrt inst | | | Extraneous PST | | | wrt marker | | | |

NOTE:

The processor's operation is perfectly correct throughout this sequence.

If a WDDATA.{B,W,L} instruction is included in the exception handler before any instructions with operand writes, the extraneous value does not occur.

If the first memory-referencing instruction in an exception handler is a write, inserting a NOP instruction immediately after it will prevent the extraneous value anomaly. If any operand reads are performed before the first write, the NOP is not required.

15.2.2.2 Non-Contiguous Stream of PST = 0xD Values During a Debug Interrupt Exception

If the debug module is configured to generate a debug interrupt exception in response to a breakpoint trigger, the processor responds by taking a special exception. While processing this exception, the debug module usually outputs a contiguous stream of PST = 0xD values until the exception completes and control is passed to the instruction defined by the interrupt vector. This change-of-flow is signaled by PST = 0x5, which marks the end of the exception processing. The only deviations to the PST = 0xD stream are operand markers (PST = 0xB) associated with operand captures during the writing of the exception stack frame.

Freescale Semiconductor, Inc.

Changes

If operand writes are being captured, sometimes the stream of PST = 0xD values is non-contiguous, and includes PST = 0x0 values. Note that the processor's operation is perfectly correct throughout this sequence.

NOTE:

The user should ignore PST = 0x0 values occurring during a debug interrupt and understand the debug interrupt exception processing to be defined from the initial PST = 0xD until the PST = 0x5 value. To ensure a contiguous stream of PST = 0xD values, disable capturing of operand writes if debug interrupts are enabled.

15.3.2,15-29 Insert a space between the bra.* instruction and the appropriate labels in the assembly language examples so they read as follows:

```
align4
label1:nop
bra.b label1
```

OR

```
align4
label2:bra.w label2
```

15.3.3.6, 15-35 In the description of the EMU bit, replace the bit description with the following text:

Do not set bit 13 of the debug module's Configuration/Status Register. The quickest entry into emulator mode after reset is created with the following sequence:

1. While in the BDM initiation sequence, program a debug breakpoint trigger event by an operand reference to address 0x0 or 0x4. As part of this sequence, the debug interrupt vector must also be initialized to the same address as the initial PC defined at address 4.
2. When the BDM “go” command is received by the processor, the reset exception processing fetches the longwords at addresses 0 and 4 in “normal mode” and then a debug interrupt is immediately generated before the first instruction is executed.
3. Execution continues in emulator mode.

15.4, 15-38 Modify Figure 15-7 to show pin 9 as an output – draw an arrow starting on the connector rectangle and pointing toward the “+5V” label.

Add the following notes to Figure 15-7 describing Motorola's recommended BDM pinout on the 26-pin Berg connector.

Although pin 9 is labeled “+5V”, the appropriate voltage sourced by pin 9 is BDM-tool-vendor specific. On the Motorola MCF5206eC3 evaluation boards this pin's voltage is jumper-selectable between 3.3v

Freescale Semiconductor, Inc.

Changes

and 5v. Check with your tools vendor to determine the correct value in your case.

Pin 21, labeled “Motorola reserved,” may be left floating.

intro, 16-1

Strike out the words, “either asserting $\overline{\text{TRST}}$ or”, in the second paragraph so that it reads as follows:

. . . This architecture provides access to all of the data and chip control pins from the board edge connector through the standard four-pin test access port (TAP). ~~and the active-low JTAG reset pin, $\overline{\text{TRST}}$. . .~~

16.2, 16-2

Replace every instance of $\overline{\text{JTAG}}$ with MTMOD. Note the overbar on $\overline{\text{JTAG}}$. Replace only those instances with the overbar.

16.3.1.2, 16-4

Strike out the words, “either asserting $\overline{\text{TRST}}$ or”, in the second paragraph so that it reads as follows:

The IDCODE instruction is the default value placed in the instruction register when a JTAG reset is accomplished by ~~either asserting $\overline{\text{TRST}}$ or~~ holding TMS high while clocking TCK through at least five rising edges and the falling edge after the fifth rising edge.

16.6, 16-8, 9

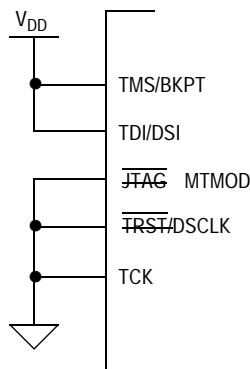
Change all instances of $\overline{\text{JTAG}}$ to MTMOD. Modify the last sentence of paragraph 16.6 so that it reads as follows:

. . . (disconnection) or intentional fixing of TAP logic values, and 2) Intentional disabling of the JTAG test logic by assertion of the MTMOD signal (entering Debug mode)

16.6, 16-8, 9

Modify the last sentence of the second paragraph and Figure 16-3 so they appear as follows:

Figure 16-3 shows pin values recommended for disabling JTAG with the MCF5206e in JTAG mode (MTMOD=0).



Freescale Semiconductor, Inc.

Changes

16.6, 16-8, 9

Strike out the references to $\overline{\text{TRST}}$ in the excerpt from the second paragraph shown below so that it reads as follows:

... This requires the minimum of ~~either connecting the $\overline{\text{TRST}}$ pin to logic 0, or connecting the TCK clock pin to a clock source that will supply five rising edges and the falling edge after the fifth rising edge, to ensure that the part enters the test-logic-reset state. The recommended solution is to connect $\overline{\text{TRST}}$ to logic 0.~~ Another consideration is that the TCK pin does not have an internal pull-up as is required on the TMS, TDI, and $\overline{\text{TRST}}$ pins; therefore, it should not be left unterminated to preclude mid-level input values.

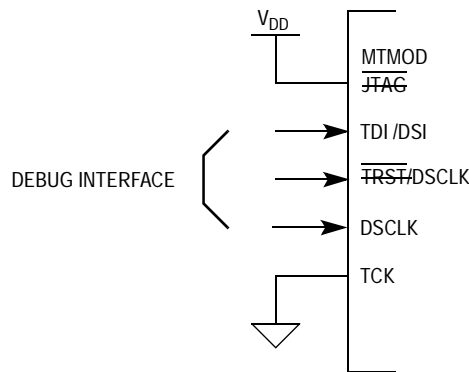
16.6, 16-8, 9

Change $\overline{\text{JTAG}}$ to MTMOD and strike out the reference to $\overline{\text{TRST}}$ in the last paragraph so that it reads as follows:

A second method of using the MCF5206e without the IEEE 1149.1 logic being active is to select debug mode by placing a logic 1 on the defined compliance enable pin, MTMOD. When MTMOD is a logic 1, then the IEEE 1149.1 test controller is placed in the test-logic-reset state ~~by the internal assertion of the $\overline{\text{TRST}}$ signal to the controller,~~ and the TAP pins function as Debug mode pins. While in JTAG mode, input pins TDI/DSI, TMS/BKPT, and $\overline{\text{TRST}}$ /DSCLK have internal pull-ups enabled.

16.6, 16-8, 9

Modify Figure 16-4 as shown below:



17.1., 17-1 Add the following paragraph and table:

17.1.1a Power Consumption

| Frequency (MHz) | Power Dissipation, Typical (mW) |
|-----------------|---------------------------------|
| 40 | 340 |
| 54 | 460 |

17.1.1b Low-Power State

Example power consumption for the 5206e in low-power state (after STOP instruction) is shown in Table 17-1.1.

NOTE:

The low-power consumption numbers given below were derived from a single set of measurements and are not statistically representative of the MCF5206e. Motorola makes no guarantees regarding these values. They are provided as an example only. Your results may vary.

Table 17-1.1. Example Power Consumption in Low-Power State

| Clock Rate in MHz | Power Dissipation in mW |
|-------------------|-------------------------|
| 54 | 287 |
| 40 | 214 |
| 25 | 142 |
| 16 | 99 |

17.1.2, 17-2 Replace the following line in Table 17-2,

| | | | |
|--|----------------|-----|----|
| Maximum operating junction temperature | T _J | TBD | °C |
|--|----------------|-----|----|

with

| | | | |
|--|----------------|------------------------------------|----|
| Maximum operating junction temperature | T _J | 95 ¹ , 105 ² | °C |
|--|----------------|------------------------------------|----|

¹ Standard temperature devices

² Extended temperature devices

17.2, 17-3

Replace Table 17-5 with the following:

Table 17.5. DC Electrical Specifications

| CHARACTERISTIC | SYMBOL | MIN | MAX | UNIT |
|--|---------------------------------------|-----|------------|---------|
| Operation voltage range | V_{DD} | 3.0 | 3.6 | V |
| Input high voltage | V_{IH} | 2 | 5.5 | V |
| Input low voltage | V_{IL} | GND | 0.8 | V |
| Input signal undershoot | — | — | 0.8 | V |
| Input signal overshoot | — | — | 0.8 | V |
| Input leakage current @ GND, $V_{IH}=5.5^1$ CLK, A[27:0], D[31:0], \overline{TS} , $SIZ[1:0]$, R/\overline{W} , \overline{TA} , \overline{ATA} , \overline{TEA} , $\overline{IPL}[2]/$ $\overline{IRQ}[7]$, $\overline{IPL}[1]/\overline{IRQ}[4]$, $\overline{IPL}[0]/\overline{IRQ}[1]$, \overline{BG} , $RxD[2:1]$, $\overline{CTS}[2:1]$, $\overline{TIN}[1:0]$, $\overline{PP}[7:0]/\overline{PST}[3:0]$, $\overline{DDATA}[3:0]$, \overline{RSTI} , \overline{TCK} , \overline{HIZ} , \overline{JTAG} , \overline{MTMOD} | I_{in} | — | 200 | μA |
| HI-Z (three-state) leakage current @GND, V_{DD} A[27:0], D[31:0], \overline{TS} , $\overline{TT}[1:0]$, \overline{ATM} , $SIZ[1:0]$, R/\overline{W} , \overline{TA} , $\overline{TDO/DSO}$ | I_{TSI} | — | 20 | μA |
| Signal Low Input Current, $V_{IL} = 0.8V$ $\overline{TMS}/\overline{BKPT}$, $\overline{TDI}/\overline{DSI}$, $\overline{TRST}/\overline{DSCLK}$ | I_{IL} | 0 | 1.0 | mA |
| Signal High Input Current, $V_{IH} = 2.0V$ $\overline{TMS}/\overline{BKPT}$, $\overline{TDI}/\overline{DSI}$, $\overline{TRST}/\overline{DSCLK}$ | I_{IH} | 0 | 1.0 | mA |
| Output high voltage, $I_{OH} = 5\text{ mA}$ (All signals ² except $\overline{RAS}[1:0]$, $\overline{CAS}[3:0]$, \overline{DRAMW} , \overline{TS} , R/\overline{W} , A[27:23]), $I_{OH} = 11\text{mA}$ ($\overline{RAS}[1:0]$, $\overline{CAS}[3:0]$, \overline{DRAMW} , \overline{TS} , R/\overline{W} , A[27:23]) | V_{OH} | 2.4 | — | V |
| Output low voltage, $I_{OL} = 5\text{ mA}$ (All signals except $\overline{RAS}[1:0]$, $\overline{CAS}[3:0]$, \overline{DRAMW} , \overline{TS} , R/\overline{W} , A[27:23]), $I_{OL} = 11\text{mA}$ ($\overline{RAS}[1:0]$, $\overline{CAS}[3:0]$, \overline{DRAMW} , \overline{TS} , R/\overline{W} , A[27:23]) | V_{OL} | — | 0.5 | V |
| Pin capacitance ³ | C_{in} | — | 10 | pF |
| ESD specification | Meets 100 V MM (machine model) | | | |

¹ Changes shown in bold face.

² Note that open-drain signals require pull-up resistors and cannot source I_{OH}

³ This specification periodically sampled but not 100% tested.

17.3.3, 17-5

In Table 17-8, change the Min specification for B1f to 3.0 ns for the 40 MHz device and 2.0 ns for the 54 MHz device.

In Table 17-8, change the Min specification for B5 to 7.0 ns for the 40 MHz device and 3.5 ns for the 54 MHz device.

17.3.3, 17-6

Add the following paragraph:

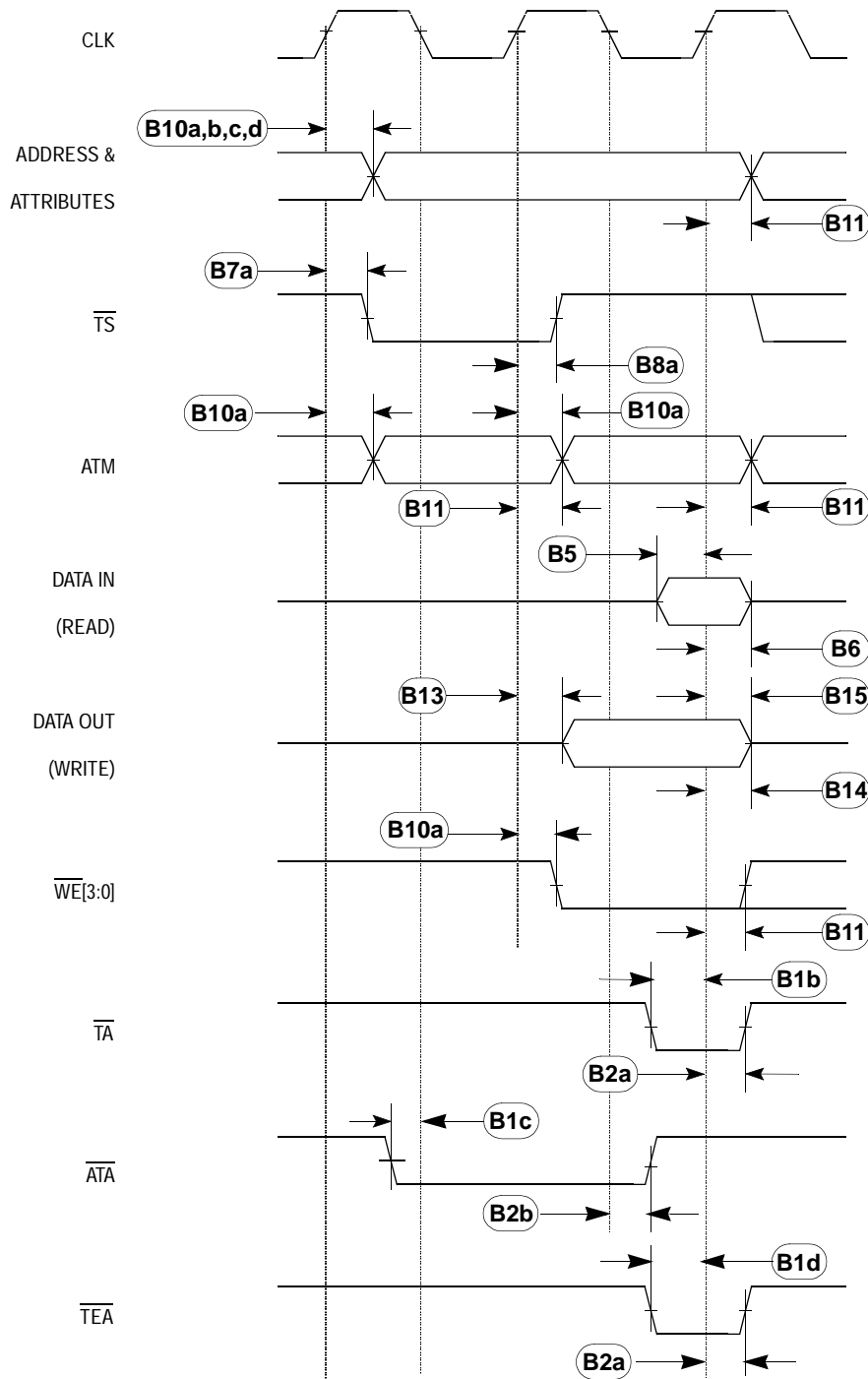
Although output signals that share a specification number have approximately the same timing, due to loading differences they do not necessarily change at the same time. However, they have similar timings; that is, minimum and maximum times are not mixed.

Freescale Semiconductor, Inc.

Changes

17.3.7, 17-10

Replace Figure 17-5 with the following:



NOTE: ADDRESS AND ATTRIBUTES REFER TO THE FOLLOWING SIGNALS:
A[27:0], SIZ[1:0], R/W, TT[1:0], ATM, and CS[7:0].

Figure 17-5. Read and Write Timing

Freescale Semiconductor, Inc.

Changes

- 17.3.8, 17-15 In Table 17-9, change the Min specification for T2 to 5.0 ns for the 40 MHz device and 3.0 ns for the 54 MHz device.
- 17.3.10, 17-17 In Table 17-11, change the Min specification for U1 to 3.0 ns for the 40 MHz device and 2.0 ns for the 54 MHz device. Also, change the column heading in the last column from NAME to UNIT.
- 17.3.12.1, 17-18 In Table 17-12, “INPUT Timing Specifications Between SCL and SDA,” change the Max specification for M3 to 1 mS for both clock speeds. Change the Max specification for M5 to 1 mS for both clock speeds.
- 17.3.12.2, 17-19 In Table 17-13, “Output Timing Specifications Between SCL and SDA,” change the Max specification for M5 from TBD to 3 μ S for both clock speeds.
- 17.3.12.3, 17-19,20 Delete this section heading and Table 17-14, “Timing Specifications Between CLK and SCL, SDA.” Also delete the associated timing diagram Figure 17-13, “M-Bus Timing.”
- 17.3.14, 17-21 In Table 17-15, change the Min specification for P1 to 4.5 ns for the 40 MHz device and 3.0 ns for the 54 MHz device.
- 17.3.18, 17-21, 22 Strike out the timing information for $\overline{\text{TRST}}$ depicted in Table 17-16 and Figure 17-16.
- 18.1, 18-2 Change the label on pin 27 of Figure 18-1, from VSS to GND.
- Figure 18-1., 18-2 On the package diagram and pinout figure, strike out $\overline{\text{TRST}}$ and replace $\overline{\text{JTAG}}$ with MTMOD.
- Appendix A-iv Change PPDDR to PADDR.
Change PPDAT to PADAT.
- Appendix A Add the following entry to Appendix A.
- | | | | | | |
|------|-------|---|---|------|-----|
| \$07 | MPARK | 8 | Bus Master Arbitration Control Register | \$00 | R/W |
|------|-------|---|---|------|-----|
- Index-7 Add an overbar to TS in Transfer Start index entry.

Appendix C

1.1 Basic DRAM Parameters

Refresh size is the number of row addresses that must be cycled through to keep the DRAM refreshed. A 4K refresh DRAM uses 12 row address bits ($2^{12} = 4K$), and an 8K refresh DRAM uses 13 row address bits.

The number of column address bits and the data bus width determine a DRAM's page size:

(page size in bytes) = (data bus width in bytes) * $2^{\text{(number of column address bits)}}$

A 16-bit DRAM with 9 column address bits has a page size of 1KB.

The basic “size” or storage capacity of a DRAM is the page size multiplied by the refresh size. A DRAM with an 8K refresh and 1KB page size has an 8MB capacity.

When two 16-bit DRAMs are arranged in “parallel” to provide a 32-bit data bus (one chip on D31..D16 and another on D15..D0), the processor should be configured for an effective page size equal to twice the page size of one chip, because twice as much memory can be accessed in this configuration without changing the row address.

A larger page size requires more circuitry inside the DRAM chip but improves overall performance by reducing both the number of rows to refresh and the amount of page switching.

1.2 Asymmetrical DRAM

When a DRAM has the same number of row addresses as column addresses it is called symmetrical. When the number of row and column addresses are not the same the DRAM is called asymmetrical. Most currently available DRAM is asymmetrical. All existing asymmetrical DRAMs have more rows, and therefore more row address lines, than columns and column address lines. In a transaction with an asymmetrical DRAM, the complete row address is transferred first, then the column address is transferred using the least significant address lines. If the processor is configured to use the same page size as the “effective” page size of the DRAM, the DRAM should be connected to consecutive address lines on the processor. The connection is illustrated in the following example.

Table 11-8.1 Two 16-bit asymmetric 1KB page size chips in “parallel” to form a 32-bit data bus with 2KB page size

| MCF5206e Address Pin | Port Size = 16-bit BankPage = 2 Kbyte | | Address line on DRAM |
|----------------------------|--|-------------------|-------------------------|
| | Row address | Column Address | |
| A11 | IA11 | IA2 | A0 |
| A12 | IA12 | IA3 | A1 |
| A13 | IA13 | IA4 | A2 |
| A14 | IA14 | IA5 | A3 |
| A15 | IA15 | IA6 | A4 |
| A16 | IA16 | IA7 | A5 |
| A17 | IA17 | IA8 | A6 |
| A18 | IA18 | IA9 | A7 |
| A19 | IA19 | IA10 | A8 |
| A20 | IA20 | | A9 |
| A21 | IA21 | | A10 |
| A22 | IA22 | | A11 |
| A23 | IA23 | | A12 |

Section 11.3.2.4 describes connections for symmetrical DRAM. Symmetrical DRAM addresses are transferred in two equal parts, with most of the row address first, then the rest of the row address on the more significant bits and the column address on the less significant bits. By making the two transfers of equal size rather than using a large row address transfer followed by a small column address transfer like asymmetrical DRAM does, fewer physical address lines are needed on the DRAM. Because the bits of the row address that are transferred with the column address use some of the same physical connections as some of the bits of the row address that were transferred previously, some of the address lines from the processor should be skipped as shown by not being shaded in Tables 11-6, 11-7 and 11-8.

In some cases, such as when connecting two 16-bit asymmetrical DRAM's with 2KB page size in “parallel” to a 32-bit data bus, the resulting 4KB “effective” page size is larger than the 5206e can handle directly using the asymmetrical method described above. The DRAM chips have more column address bits than the number of consecutive column addresses

Freescale Semiconductor, Inc.

Changes

provided by the processor's multiplexing scheme. In such cases the extra DRAM column address bits can be controlled by row address bits from the processor. This effectively breaks up each of the bigger DRAM pages into what appears to the processor to be 2, 4, 8 (or more) different pages. The performance is the same as if a DRAM with the page size the processor is configured for was used, because the processor inserts page switching delays (transfers a new row address, etc.) whenever it thinks it is switching pages, even though the “new page” (as seen by the processor) may actually be on the same page in the DRAM (if the only processor row address bits that change are the ones connected to DRAM column address bits).

The address line connections for interfacing DRAMs with a larger effective page size than the processor configuration is a combination of the symmetrical and asymmetrical methods. The number of column address lines that the DRAMs use should be connected (starting with the least significant line) as shown in the manual for the symmetrical case (including skipping some of the processor's address lines). Then the remaining address lines (which the DRAMs use for the row but not column address) should be connected consecutively, as in the asymmetrical case. The most significant processor address line used should correspond with the size of the memory (A23 => 16MB, etc.).

Example: Two 16-bit asymmetric 1KB page size chips in “parallel” to get 32-bit data bus while keeping a 1KB page size.

Table 1. Two 16-bit asymmetric 1KB page size chips in “parallel” forming a 32-bit data bus with a 1KB page size

| MCF5206e Address Pin | Port Size = 16-bit BankPage = 2 Kbyte | | Address line on DRAM |
|----------------------------|--|-------------------|-------------------------|
| | Row address | Column Address | |
| A10 | IA10 | IA2 | A0 |
| A11 | IA11 | IA3 | A1 |
| A12 | IA12 | IA4 | A2 |
| A13 | IA13 | IA5 | A3 |
| A14 | IA14 | IA6 | A4 |
| A15 | IA15 | IA7 | A5 |
| A16 | IA16 | IA8 | A6 |
| A17 | IA17 | IA9 | A7 |
| A19 | IA19 | IA18 | A8 |
| A20 | IA20 | | A9 |
| A21 | IA21 | | A10 |
| A22 | IA22 | | A11 |
| A23 | IA23 | | A12 |

Example: Two 16-bit asymmetric 2KB page size chips in “parallel” to get 32-bit data bus while keeping a 2KB page size.

Freescale Semiconductor, Inc.

Changes

Table 2. Two 16-bit asymmetric 2KB page size chips in “parallel” forming a 32-bit data bus with a 2KB page size

| MCF5206e Address Pin | Port Size = 16-bit BankPage = 2 Kbyte | | Address line on DRAM |
|----------------------------|--|-------------------|-------------------------|
| | Row address | Column Address | |
| A11 | IA11 | IA2 | A0 |
| A12 | IA12 | IA3 | A1 |
| A13 | IA13 | IA4 | A2 |
| A14 | IA14 | IA5 | A3 |
| A15 | IA15 | IA6 | A4 |
| A16 | IA16 | IA7 | A5 |
| A17 | IA17 | IA8 | A6 |
| A18 | IA18 | IA9 | A7 |
| A19 | IA19 | IA10 | A8 |
| A21 | IA21 | IA20 | A9 |
| A22 | IA22 | | A10 |
| A23 | IA23 | | A11 |

Freescale Semiconductor, Inc.

Changes

Freescale Semiconductor, Inc.

Freescale Semiconductor, Inc.


Freescale Semiconductor, Inc.

DigitalDNA and Mfax are trademarks of Motorola, Inc.

The PowerPC name, the PowerPC logotype, and PowerPC 603e are trademarks of International Business Machines Corporation used by Motorola under license from International Business Machines Corporation.

Information in this document is provided solely to enable system and software implementers to use PowerPC microprocessors. There are no express or implied copyright licenses granted hereunder to design or fabricate PowerPC integrated circuits or integrated circuits based on the information in this document.

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part.

Motorola and  are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

Motorola Literature Distribution Centers:

USA/EUROPE: Motorola Literature Distribution; P.O. Box 5405; Denver, Colorado 80217; Tel.: 1-800-441-2447 or 1-303-675-2140;
World Wide Web Address: <http://ldc.nmd.com/>

JAPAN: Nippon Motorola Ltd SPD, Strategic Planning Office 4-32-1, Nishi-Gotanda Shinagawa-ku, Tokyo 141, Japan Tel.: 81-3-5487-8488

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd Silicon Harbour Centre 2, Dai King Street Tai Po Industrial Estate Tai Po, New Territories, Hong Kong

Mfax™: RMFAX0@email.sps.mot.com; TOUCHTONE 1-602-244-6609; US & Canada ONLY (800) 774-1848;

World Wide Web Address: <http://sps.motorola.com/mfax>

INTERNET: <http://motorola.com/sps>

Technical Information: Motorola Inc. SPS Customer Support Center 1-800-521-6274; electronic mail address: crc@wmkmail.sps.mot.com.

Document Comments: FAX (512) 895-2638, Attn: RISC Applications Engineering.

World Wide Web Addresses: <http://www.motorola.com/PowerPC>

<http://www.motorola.com/netcomm>

<http://www.motorola.com/Coldfire>



MOTOROLA

MCF5206EUMAD

**For More Information On This Product,
Go to: www.freescale.com**